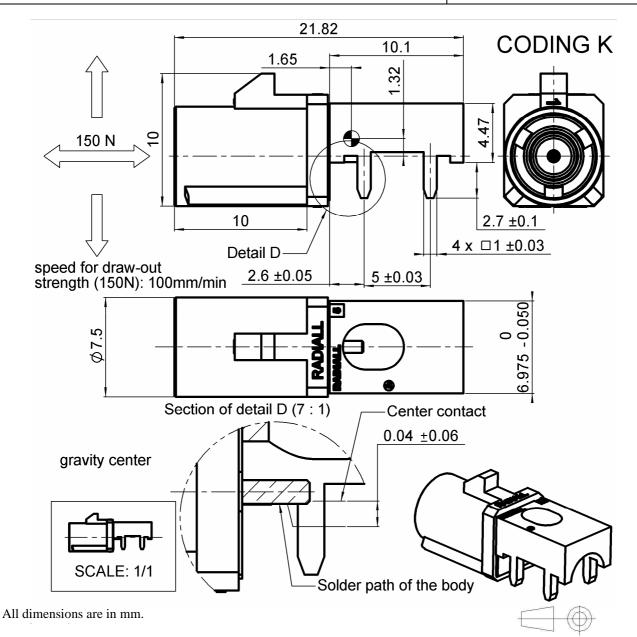
EDGE CARD - PIN IN PASTE VERSION

R197.160.K18

Series: SMB CARLOCK



COMPONENTS	MATERIALS	PLATING (μm)		
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	ZINC ALLOY BRASS - PTFE -	TIN FOR HI TEMPERATURE GOLD 0.5 OVER NICKEL 2		
-	-	UL CLASSIFICATION	COLOR	
HOUSING	PA 4.6 30%GF	UL 94 V2 * According to	CURRY RAL 1027	

Issue: 0943 C

In the effort to improve our products, we reserve the right to make changes judged to be



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PACKAGING

Standard	Unit	Other
350	'W' option	Contact us

SPECIFICATION

QS9000 SN 55228-2**

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-4} \;\; \text{GHz} \end{array}$

VSWR 1.06* + 0,0130 x F(GHz) Maxi

Insertion loss RF leakage 0.03 $\sqrt{F(GHz)}$ dB Maxi - (GHz) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 Veff mini 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -40/+110 ° C

Hermetic seal NA Atm.cm3/s
Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

*COAX TRANSMISSION LINE ONLY **Complaint except that 2D label does not include the shipping note number.

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 50 Cycles mini

Weight 2,2273 g

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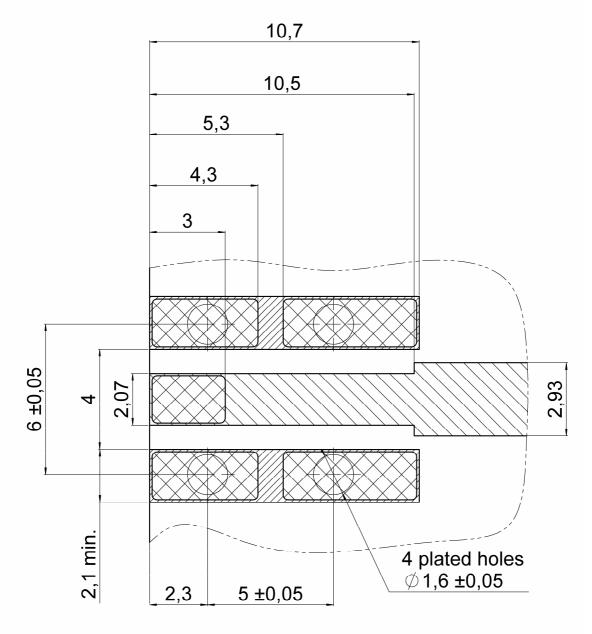


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MOUNTING ZONE FOR RECEPTACLE



Thickness of PCB: 1,6 mm. Material of PCB: FR4 ($\varepsilon r = 4.6$). Solder paste has to be printed onto the land of solder and into holes to permit Pin In Hole Reflow Ground track





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SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

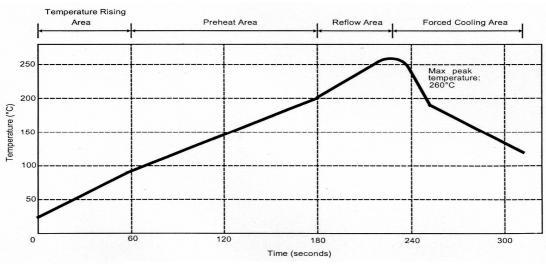
We advise a thickness of 0.2 millimetres min. (0.008 inch min.). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec

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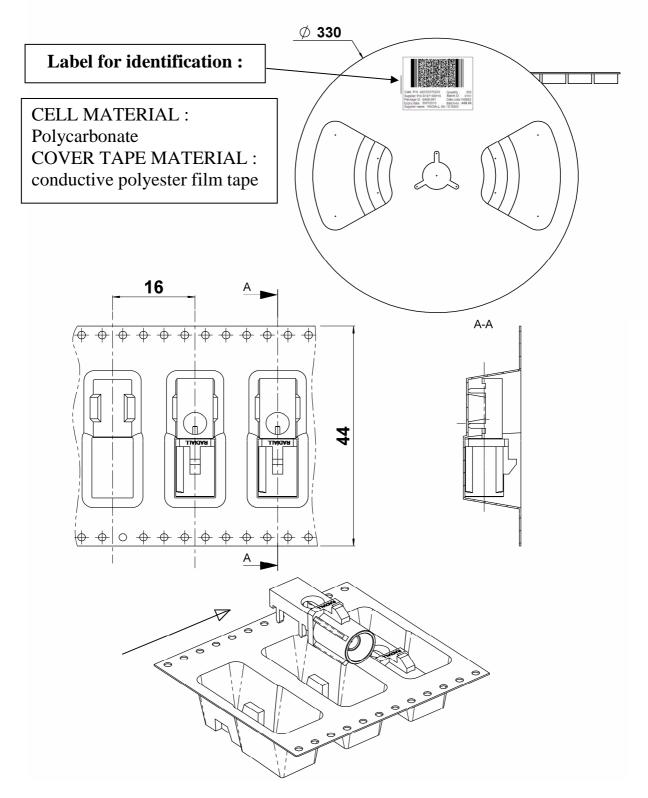


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REEL PACKAGING PER 350



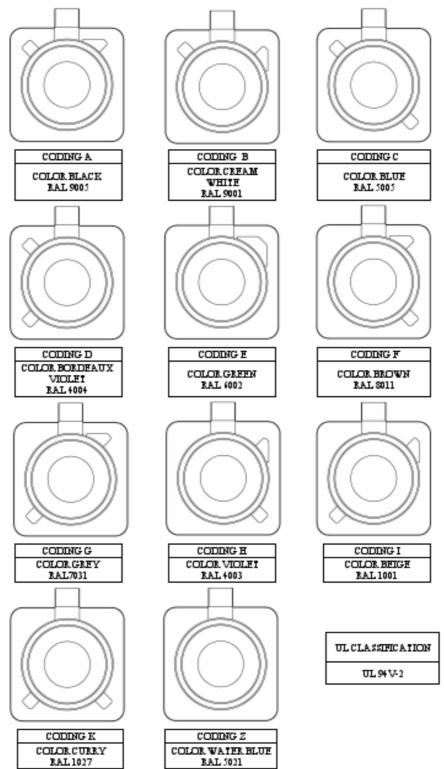
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Series: SMB CARLOCK



*According to FAKRA specifications

To obtain other coding for the connector please change the letter by the needed coding letter into the Part Number

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